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Nota di contenuto	Contents; Abstracts & keywords; Editorial; Correlation of solder paste rheology with computational simulations of the stencil printing process; Solder paste reflow modeling; Numerical modelling of scanned beam laser soldering of fine pitch packages; A simplified model of the reflow soldering process; CFD modelling of the flow field inside a reflow oven; Analysis on solder ball shear testing conditions with a simple computational model; Optimisation modelling for flip-chip solder joint reliability; Internet commentary; Book review; Industry news; Appointments; International diary Note from the publisher
Sommario/riassunto	This special issue of SSMT brings together seven papersdemonstrating the latest achievements in the applications ofcomputational modelling technology to soldering processesand solder joint reliability.Why use computational models?The performance of soldering materials during productassembly is governed by complex interacting physicalphenomena.